

2.3 PCB hole size should be 1 mm in diameter (check drawing tolerances).

3.0 Component Pre-forming

3.1 Component legs should be pre-formed, if necessary, **before** installation to the PCB.

3.2 Attention should be paid to ensuring that the body of the device is not used as a fulcrum when the leads are being pre-formed.

3.3 Attention should be paid to ensuring that stress is not applied to the pins during installation into the circuit board.

4.0 Circuit Design

4.1 The correct method of connecting the backlight emitters is to wire them in series with a current limiting resistor.

4.2 If parallel connection is required, then each emitter should have a separate series limiting resistor (for clarification and more details see our latest backlight catalogue)

5.0 Cleaning

5.1 It is essential that cleaning agents used are tested with the backlight as some solvents will remove the backing layer from the light guide.

5.2 Suggested cleaning agents include Isopropanol and other alcohol based materials, (not to be used on painted surfaces). Use only a short cleaning process.

5.3 Solvents such as Trichloroethane are known to damage the light guide.

6.0 Product Handling

6.1 Static handling precautions: Whilst this type of L.E.D. product is not normally regarded as static sensitive, statistical studies have shown that the medium to long term M.T.B.F. performance is enhanced by anti-static handling precautions of all semi-conductors, which are therefore suggested with reference to this product.

Authority:



Ruth Smaldon
Quality Systems Manager.